

Title (en)

Process and device for manufacturing lacquered wires molten resins.

Title (de)

Verfahren und Vorrichtung zur Herstellung von Lackdrähten mit Schmelzharzen.

Title (fr)

Procédé et dispositif de fabrication de fils recouverts d'un vernis à base de résines fondues.

Publication

EP 0448999 B1 19950802 (DE)

Application

EP 91103406 A 19910306

Priority

DE 4010306 A 19900330

Abstract (en)

[origin: EP0448999A2] For manufacturing lacquered wires with virtually solvent-free molten resins, as far as the process is concerned, the bare wire is prepared for coating in a way dependent on the material, a supply of resin for the coating is melted and kept by the application of heat at a temperature to obtain suitable viscosity for coating, the molten resin is pumped along under positive pressure against the direction of movement of the wire over a predetermined length of the said wire, over its entire circumference, parts of the resin coating the wire, whereas the excess resin and the resin coating the wire and then calibrated to a predetermined circumferential size is returned to the supply. The resin coating the wire is subsequently cured. As far as the device is concerned, a coating device comprises a wire preparing device, in particular for the wire to be cleaned, heated and the like for its material-dependent preparation, a resin preparation device, a resin application device, the resin preparation device and resin application device being arranged in the form of a closed circuit, as well as a stoving oven. <IMAGE>

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IPC 8 full level

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CPC (source: EP US)

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Cited by

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EP 0448999 A2 19911002; **EP 0448999 A3 19920506**; **EP 0448999 B1 19950802**; DE 4010306 A1 19911002; DE 4010306 C2 19990610; DE 59106107 D1 19950907; ES 2076388 T3 19951101; JP 2960184 B2 19991006; JP H07114844 A 19950502; US 5492721 A 19960220

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